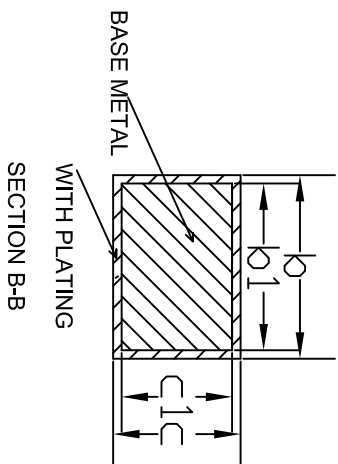
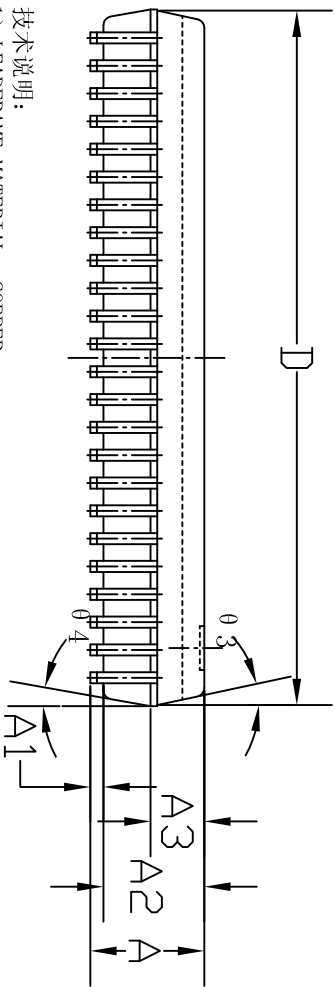
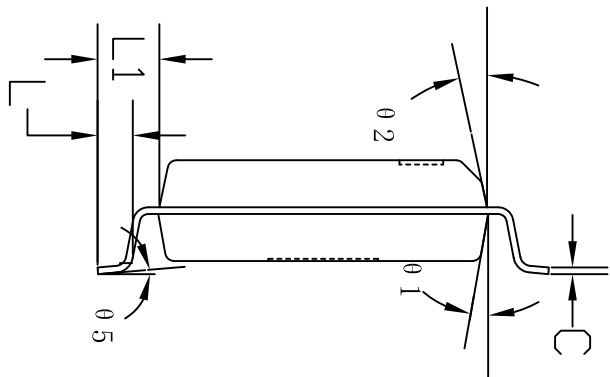
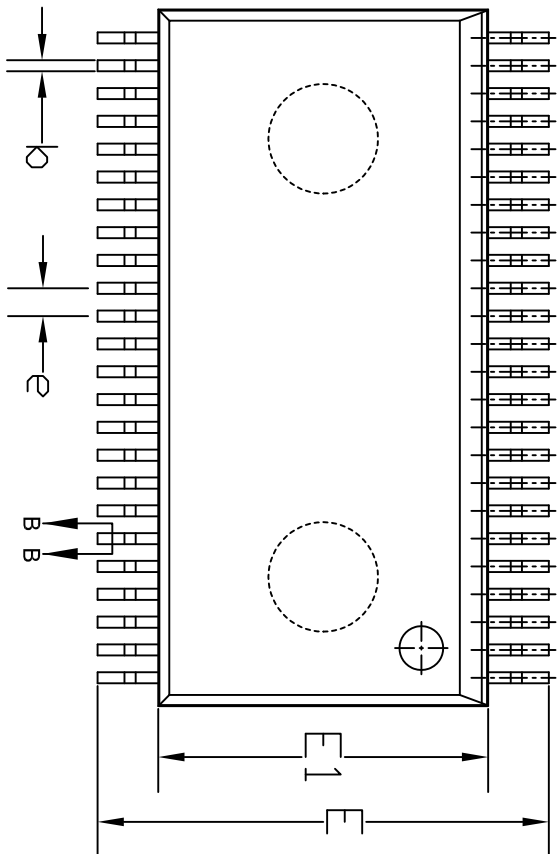




SSOP48 PACKAGE OUTLINE DIMENSIONS



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	2.85
A1	0.15	0.30	0.45
A2	2.10	2.30	2.45
A3	1.10	1.23	1.35
b	0.22	--	0.32
b1	0.20	0.25	0.30
c	0.12	--	0.21
c1	0.10	0.16	0.20
D	15.60	15.85	16.05
E	9.80	10.30	10.80
E1	7.35	7.48	7.65
e	0.64(BSC)		
L	0.56	0.76	0.95
L1	1.41(REF)		
theta 1	6°	~	15°
theta 2	8°	~	16°
theta 3	8°	~	16°
theta 4	6°	~	15°
theta 5	0°	~	8°

技术说明:

1) LEADFRAME MATERIAL: COPPER;

引线框架材料: 铜;

2) LEADFRAME THICKNESS: 0.152mm;

引线框架厚度: 0.152mm;

3) BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;

塑封体长度及宽度尺寸不包括塑封溢胶;

4) REFERENCE: JEDEC MS-013, MS-012.

参考标准: JEDEC MS-013, MS-012.